Intel - EP4CE40F29I7N Datasheet





Welcome to <u>E-XFL.COM</u>

Understanding <u>Embedded - FPGAs (Field</u> <u>Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

| Product Status | Active |
|--------------------------------|--|
| Number of LABs/CLBs | 2475 |
| Number of Logic Elements/Cells | 39600 |
| Total RAM Bits | 1161216 |
| Number of I/O | 532 |
| Number of Gates | - |
| Voltage - Supply | 1.15V ~ 1.25V |
| Mounting Type | Surface Mount |
| Operating Temperature | -40°C ~ 100°C (TJ) |
| Package / Case | 780-BGA |
| Supplier Device Package | 780-FBGA (29x29) |
| Purchase URL | https://www.e-xfl.com/product-detail/intel/ep4ce40f29i7n |
| | |

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1. Cyclone IV FPGA Device Family Overview

Altera's new Cyclone[®] IV FPGA device family extends the Cyclone FPGA series leadership in providing the market's lowest-cost, lowest-power FPGAs, now with a transceiver variant. Cyclone IV devices are targeted to high-volume, cost-sensitive applications, enabling system designers to meet increasing bandwidth requirements while lowering costs.

Built on an optimized low-power process, the Cyclone IV device family offers the following two variants:

- Cyclone IV E—lowest power, high functionality with the lowest cost
- Cyclone IV GX—lowest power and lowest cost FPGAs with 3.125 Gbps transceivers

Cyclone IV E devices are offered in core voltage of 1.0 V and 1.2 V.

To For more information, refer to the *Power Requirements for Cyclone IV Devices* chapter.

Providing power and cost savings without sacrificing performance, along with a low-cost integrated transceiver option, Cyclone IV devices are ideal for low-cost, small-form-factor applications in the wireless, wireline, broadcast, industrial, consumer, and communications industries.

Cyclone IV Device Family Features

The Cyclone IV device family offers the following features:

- Low-cost, low-power FPGA fabric:
 - 6K to 150K logic elements
 - Up to 6.3 Mb of embedded memory
 - Up to 360 18 × 18 multipliers for DSP processing intensive applications
 - Protocol bridging applications for under 1.5 W total power

^{© 2016} Altera Corporation. All rights reserved. ALTERA, ARRIA, CYCLONE, HARDCOPY, MAX, MEGACORE, NIOS, QUARTUS and STRATIX words and logos are trademarks of Altera Corporation and registered in the U.S. Patent and Trademark Office and in other countries. All other words and logos identified as trademarks or service marks are the property of their respective holders as described at www.altera.com/common/legal.html. Altera warrants performance of its semiconductor products to current specifications in accordance with Altera's standard warranty, but reserves the right to make changes to any products and services at any time without notice. Altera asumes no responsibility or liability arising out of the application or use of any information, product, or service described herein except as expressly agreed to in writing by Altera. Altera customers are advised to obtain the latest version of device specifications before relying on any published information and before placing orders for products or services.



Asynchronous Clear

Cyclone IV devices support asynchronous clears for read address registers, output registers, and output latches only. Input registers other than read address registers are not supported. When applied to output registers, the asynchronous clear signal clears the output registers and the effects are immediately seen. If your RAM does not use output registers, you can still clear the RAM outputs using the output latch asynchronous clear feature.

Asserting asynchronous clear to the read address register during a read operation may corrupt the memory content.

Figure 3–5 shows the functional waveform for the asynchronous clear feature.

Figure 3–5. Output Latch Asynchronous Clear Waveform



You can selectively enable asynchronous clears per logical memory using the Quartus II RAM MegaWizard[™] Plug-In Manager.

For more information, refer to the *RAM Megafunction User Guide*.

There are three ways to reset registers in the M9K blocks:

- Power up the device
- Use the aclr signal for output register only
- Assert the device-wide reset signal using the DEV_CLRn option

Memory Modes

Cyclone IV devices M9K memory blocks allow you to implement fully-synchronous SRAM memory in multiple modes of operation. Cyclone IV devices M9K memory blocks do not support asynchronous (unregistered) memory inputs.

M9K memory blocks support the following modes:

- Single-port
- Simple dual-port
- True dual-port
- Shift-register
- ROM
- FIFO

3–7

| LFC[1] | LFC[0] | Setting (Decimal) |
|--------|--------|-------------------|
| 0 | 0 | 0 |
| 0 | 1 | 1 |
| 1 | 1 | 3 |

| lable 5–10. Loop Filter Control of High Frequency Capac |
|---|
|---|

Bypassing a PLL Counter

Bypassing a PLL counter results in a divide (N, C0 to C4 counters) factor of one.

Table 5–11 lists the settings for bypassing the counters in PLLs of Cyclone IV devices.

Table 5–11. PLL Counter Settings

| | | PLL So | an Ch | ain Bit | Description | | | | |
|---|---|--------|-------|---------|-------------|---|---|-------|--------------------------|
| | | | LS | SB | | | | MSB | Description |
| Х | Х | Х | Х | Х | Х | Х | Х | 1 (1) | PLL counter bypassed |
| Х | Х | Х | Х | Х | Х | Х | Х | 0 (1) | PLL counter not bypassed |

Note to Table 5–11:

(1) Bypass bit.

To bypass any of the PLL counters, set the bypass bit to 1. The values on the other bits are then ignored.

Dynamic Phase Shifting

The dynamic phase shifting feature allows the output phase of individual PLL outputs to be dynamically adjusted relative to each other and the reference clock without sending serial data through the scan chain of the corresponding PLL. This feature simplifies the interface and allows you to quickly adjust t_{CO} delays by changing output clock phase shift in real time. This is achieved by incrementing or decrementing the VCO phase-tap selection to a given C counter or to the M counter. The phase is shifted by 1/8 the VCO frequency at a time. The output clocks are active during this phase reconfiguration process.

Table 5–12 lists the control signals that are used for dynamic phase shifting.

Table 5–12. Dynamic Phase Shifting Control Signals (Part 1 of 2)

| Signal Name | Description | Source | Destination |
|------------------------|--|----------------------------|-----------------------------------|
| phasecounterselect[20] | Counter Select. Three bits decoded to select either the M or one of the C counters for phase adjustment. One address map to select all C counters. This signal is registered in the PLL on the rising edge of scanclk. | Logic array or I/O pins | PLL reconfiguration circuit |
| phaseupdown | Selects dynamic phase shift direction; 1= UP, 0 = DOWN. Signal is registered in the PLL on the rising edge of scanclk. | Logic array or I/O pins | PLL reconfiguration circuit |
| phasestep | Logic high enables dynamic phase shifting. | Logic array or I/O pins | PLL reconfiguration circuit |

Figure 6–4 shows the single-ended I/O standards for OCT without calibration. The R_S shown is the intrinsic transistor impedance.





All I/O banks and I/O pins support impedance matching and series termination. Dedicated configuration pins and JTAG pins do not support impedance matching or series termination.

 R_S OCT is supported on any I/O bank. V_{CCIO} and V_{REF} must be compatible for all I/O pins to enable R_S OCT in a given I/O bank. I/O standards that support different R_S values can reside in the same I/O bank as long as their V_{CCIO} and V_{REF} do not conflict.

Impedance matching is implemented using the capabilities of the output driver and is subject to a certain degree of variation, depending on the process, voltage, and temperature.



For more information about tolerance specification, refer to the *Cyclone IV Device Datasheet* chapter.

I/O Standards

Cyclone IV devices support multiple single-ended and differential I/O standards. Cyclone IV devices support 3.3-, 3.0-, 2.5-, 1.8-, 1.5-, and 1.2-V I/O standards.

Table 6–3 summarizes I/O standards supported by Cyclone IV devices and which I/O pins support them.

| Table 6-3. | . Cyclone IV Devices Supported I/O Standards a | nd Constraints | (Part 1 of 3) |
|------------|--|----------------|---------------|
|------------|--|----------------|---------------|

| | | | V _{CCIO} Leve | el (in V) | C | olumn I/O P | Row I/O Pins ⁽¹⁾ | | |
|---|--------------|---------------------|---------------------------|-----------|-------------|-------------|-----------------------------|-------------|------------------|
| I/O Standard | Туре | Standard Support | Input | Output | CLK, DQS | PLL_OUT | User I/O Pins | CLK, DQS | User I/O Pins |
| 3.3-V LVTTL, 3.3-V LVCMOS <i>(2)</i> | Single-ended | JESD8-B | 3.3/3.0/2.5 <i>(3)</i> | 3.3 | ~ | ~ | \checkmark | ~ | ~ |
| 3.0-V LVTTL, 3.0-V LVCMOS <i>(2)</i> | Single-ended | JESD8-B | 3.3/3.0/2.5 <i>(3)</i> | 3.0 | ~ | ~ | ~ | ~ | ~ |

Differential I/O Standard Termination

Differential I/O standards typically require a termination resistor between the two signals at the receiver. The termination resistor must match the differential load impedance of the bus (refer to Figure 6–7 and Figure 6–8).

Cyclone IV devices support differential SSTL-2 and SSTL-18, differential HSTL-18, HSTL-15, and HSTL-12, PPDS, LVDS, RSDS, mini-LVDS, and differential LVPECL.

Figure 6-7. Cyclone IV Devices Differential HSTL I/O Standard Class I and Class II Interface and Termination



Figure 6–8. Cyclone IV Devices Differential SSTL I/O Standard Class I and Class II Interface and Termination (1)



Note to Figure 6-8:

(1) Only Differential SSTL-2 I/O standard supports Class II output.

To ensure DCLK and DATA [0] are not left floating at the end of configuration, the MAX II device must drive them either high or low, whichever is convenient on your board. The DATA [0] pin is available as a user I/O pin after configuration. In the PS scheme, the DATA [0] pin is tri-stated by default in user mode and must be driven by the external host device. To change this default option in the Quartus II software, select the **Dual-Purpose Pins** tab of the **Device and Pin Options** dialog box.

The configuration clock (DCLK) speed must be below the specified system frequency to ensure correct configuration. No maximum DCLK period exists, which means you can pause configuration by halting DCLK for an indefinite amount of time.

The external host device can also monitor CONF_DONE and INIT_DONE to ensure successful configuration. The CONF_DONE pin must be monitored by the external device to detect errors and to determine when programming is complete. If all configuration data is sent, but CONF_DONE or INIT_DONE has not gone high, the external device must reconfigure the target device.

Figure 8–14 shows how to configure multiple devices using an external host device. This circuit is similar to the PS configuration circuit for a single device, except that Cyclone IV devices are cascaded for multi-device configuration.

Figure 8–14. Multi-Device PS Configuration Using an External Host



Notes to Figure 8-14:

- (1) The pull-up resistor must be connected to a supply that provides an acceptable input signal for all devices in the chain. V_{CC} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host.
- (2) Connect the pull-up resistor to the V_{CCIO} supply voltage of the I/O bank in which the nCE pin resides.
- (3) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.
- (4) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.
- (5) All I/O inputs must maintain a maximum AC voltage of 4.1 V. DATA [0] and DCLK must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

The programming hardware or download cable then places the configuration data one bit at a time on the DATA [0] pin of the device. The configuration data is clocked into the target device until CONF_DONE goes high. The CONF_DONE pin must have an external $10-k\Omega$ pull-up resistor for the device to initialize.

When you use a download cable, setting the **Auto-restart configuration after error** option does not affect the configuration cycle because you must manually restart configuration in the Quartus II software if an error occurs. Additionally, the **Enable user-supplied start-up clock (CLKUSR)** option has no effect on device initialization, because this option is disabled in the **.sof** when programming the device with the Quartus II Programmer and download cable. Therefore, if you turn on the **CLKUSR** option, you do not have to provide a clock on CLKUSR when you configure the device with the Quartus II Programmer and a download cable.

Figure 8–17 shows PS configuration for Cyclone IV devices with a download cable.



Figure 8–17. PS Configuration Using a Download Cable

Notes to Figure 8-17:

- (1) You must connect the pull-up resistor to the same supply voltage as the V_{CCA} supply.
- (2) The pull-up resistors on DATA[0] and DCLK are only required if the download cable is the only configuration scheme used on your board. This is to ensure that DATA[0] and DCLK are not left floating after configuration. For example, if you also use a configuration device, the pull-up resistors on DATA[0] and DCLK are not required.
- (3) Pin 6 of the header is a V₁₀ reference voltage for the MasterBlaster output driver. V₁₀ must match the V_{CCA} of the device. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. With the USB-Blaster, ByteBlaster II, ByteBlaster MV, and EthernetBlaster, this pin is a no connect.
- (4) The nCEO pin is left unconnected or used as a user I/O pin when it does not feed the nCE pin of another device.
- (5) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect the MSEL pins, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9 for PS configuration schemes. Connect the MSEL pins directly to V_{CCA} or GND.
- (6) Power up the V_{CC} of the ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

You can use a download cable to configure multiple Cyclone IV device configuration pins. nCONFIG, nSTATUS, DCLK, DATA[0], and CONF_DONE are connected to every device in the chain. All devices in the chain utilize and enter user mode at the same time because all CONF DONE pins are tied together.

In addition, the entire chain halts configuration if any device detects an error because the nSTATUS pins are tied together. Figure 8–18 shows the PS configuration for multiple Cyclone IV devices using a MasterBlaster, USB-Blaster, ByteBlaster II, or ByteBlasterMV cable.





Notes to Figure 8-18:

- (1) You must connect the pull-up resistor to the same supply voltage as the V_{CCA} supply.
- (2) The pull-up resistors on DATA[0] and DCLK are only required if the download cable is the only configuration scheme used on your board. This ensures that DATA[0] and DCLK are not left floating after configuration. For example, if you also use a configuration device, the pull-up resistors on DATA[0] and DCLK are not required.
- (3) Pin 6 of the header is a V_{I0} reference voltage for the MasterBlaster output driver. V_{I0} must match the V_{CCA} of the device. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the ByteBlasterMV download cable, this pin is a no connect. When using USB-Blaster, ByteBlaster II, and EthernetBlaster cables, this pin is connected to nCE when it is used for AS programming. Otherwise, it is a no connect.
- (4) Connect the pull-up resistor to the V_{CCIO} supply voltage of the I/O bank in which the nCE pin resides.
- (5) The nCEO pin of the last device in the chain is left unconnected or used as a user I/O pin.
- (6) The MSEL pin settings vary for different configuration voltage standards and POR time. To connect MSEL for PS configuration schemes, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the MSEL pins directly to V_{CCA} or GND.
- (7) Power up the V_{CC} of the ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5 V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the MasterBlaster Serial/USB Communications Cable User Guide.

When programming a JTAG device chain, one JTAG-compatible header is connected to several devices. The number of devices in the JTAG chain is limited only by the drive capability of the download cable. When four or more devices are connected in a JTAG chain, Altera recommends buffering the TCK, TDI, and TMS pins with an on-board buffer.

JTAG-chain device programming is ideal when the system contains multiple devices, or when testing your system with JTAG BST circuitry. Figure 8–25 and Figure 8–26 show multi-device JTAG configuration.

For devices using 2.5-, 3.0-, and 3.3-V V_{CCIO} supply, you must refer to Figure 8–25. All I/O inputs must maintain a maximum AC voltage of 4.1 V because JTAG pins do not have the internal PCI clamping diodes to prevent voltage overshoot when using 2.5-, 3.0-, and 3.3- V V_{CCIO} supply. You must power up the V_{CC} of the download cable with a 2.5-V V_{CCA} supply. For device using V_{CCIO} of 1.2, 1.5 V, and 1.8 V, refer to Figure 8–26. You can power up the V_{CC} of the download cable with the supply from V_{CCIO}.

Figure 8–25. JTAG Configuration of Multiple Devices Using a Download Cable (2.5, 3.0, and 3.3-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8-25:

- (1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.
- (2) Connect the nCONFIG and MSEL pins to support a non-JTAG configuration scheme. If you only use a JTAG configuration, connect the nCONFIG pin to logic-high and the MSEL pins to GND. In addition, pull DCLK and DATA [0] to either high or low, whichever is convenient on your board.
- (3) Pin 6 of the header is a V₁₀ reference voltage for the MasterBlaster output driver. V₁₀ must match the V_{CCA} of the device. For this value, refer to the MasterBlaster Serial/USB Communications Cable User Guide. In the ByteBlasterMV cable, this pin is a no connect. In the USB-Blaster and ByteBlaster II cables, this pin is connected to nCE when it is used for AS programming, otherwise it is a no connect.
- (4) You must connect the nCE pin to GND or driven low for successful JTAG configuration.
- (5) Power up the V_{CC} of the ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.
- (6) Resistor value can vary from 1 k Ω to 10 k Ω .

- JTAG configuration allows an unlimited number of Cyclone IV devices to be cascaded in a JTAG chain.
- For more information about configuring multiple Altera devices in the same configuration chain, refer to the *Configuring Mixed Altera FPGA Chains* chapter in volume 2 of the *Configuration Handbook*.

Figure 8–27 shows JTAG configuration with a Cyclone IV device and a microprocessor.





Notes to Figure 8-27:

- (1) You must connect the pull-up resistor to a supply that provides an acceptable input signal for all devices in the chain.
- (2) Connect the nCONFIG and MSEL pins to support a non-JTAG configuration scheme. If you only use a JTAG configuration, connect the nCONFIG pin to logic-high and the MSEL pins to GND. In addition, pull DCLK and DATA[0] to either high or low, whichever is convenient on your board.
- (3) You must connect the nCE pin to GND or driven low for successful JTAG configuration.
- (4) All I/O inputs must maintain a maximum AC voltage of 4.1 V. Signals driving into TDI, TMS, and TCK must fit the maximum overshoot outlined in Equation 8–1 on page 8–5.

Configuring Cyclone IV Devices with Jam STAPL

Jam[™] STAPL, JEDEC standard JESD-71, is a standard file format for in-system programmability (ISP) purposes. Jam STAPL supports programming or configuration of programmable devices and testing of electronic systems, using the IEEE 1149.1 JTAG interface. Jam STAPL is a freely licensed open standard. The Jam Player provides an interface for manipulating the IEEE Std. 1149.1 JTAG TAP state machine.

C For more information about JTAG and Jam STAPL in embedded environments, refer to *AN 425: Using Command-Line Jam STAPL Solution for Device Programming*. To download the Jam Player, visit the Altera website (www.altera.com).

Configuring Cyclone IV Devices with the JRunner Software Driver

The JRunner software driver allows you to configure Cyclone IV devices through the ByteBlaster II or ByteBlasterMV cables in JTAG mode. The supported programming input file is in **.rbf** format. The JRunner software driver also requires a Chain Description File (**.cdf**) generated by the Quartus II software. The JRunner software driver is targeted for embedded JTAG configuration. The source code is developed for the Windows NT operating system (OS). You can customize the code to make it run on your embedded platform.

| Pin Name | User Mode | Configuration Scheme | Pin Type | Description |
|------------------|---|-------------------------|-----------------------------|--|
| CONF_DONE | N/A | All | Bidirectional open-drain | Status output—the target Cyclone IV device drives the CONF_DONE pin low before and during configuration. After all the configuration data is received without error and the initialization cycle starts, the target device releases CONF_DONE. Status input—after all the data is received and CONF_DONE goes high, the target device initializes and enters user mode. The CONF_DONE pin must have an |
| | | | | external 10-kΩ pull-up resistor in order for the device to initialize. Driving CONF_DONE low after configuration and initialization does not affect the configured device. Do not connect hus |
| | | | | holds or ADC to CONF_DONE pin. |
| nCE | N/A | All | Input | Active-low chip enable. The nCE pin activates the Cyclone IV device with a low signal to allow configuration. You must hold nCE pin low during configuration, initialization, and user-mode. In a single-device configuration, you must tie the nCE pin low. In a multi-device configuration, nCE of the first device is tied low while its nCEO pin is connected to nCE of the next device in the chain. You must hold the nCE pin low for successful JTAG programming of the device. |
| | N/A if option is on. | | Output | Output that drives low when configuration is complete. In a single-device configuration, you can leave this pin floating or use it as a user I/O pin after configuration. In a multi-device configuration, this pin feeds the nCE pin of the next device. The $nCEO$ of the last device in the chain is left floating or used as a user I/O pin after configuration. |
| nCEO | N/A if option is on. I/O if option is off. | | open-drain | If you use the nCEO pin to feed the nCE pin of the next device, use an external 10-k Ω pull-up resistor to pull the nCEO pin high to the V _{CCIO} voltage of its I/O bank to help the internal weak pull-up resistor. |
| | | | | If you use the nCEO pin as a user I/O pin after configuration, set the state of the pin on the Dual-Purpose Pin settings. |
| nCSO, | | | | Output control signal from the Cyclone IV device to the serial configuration device in AS mode that enables the configuration device. This pin functions as nCSO in AS mode and FLASH_nCE in AP mode. |
| FLASH_nCE (1) | Ι/Ο | AS, AP <i>(2)</i> | Output | Output control signal from the Cyclone IV device to the parallel flash in AP mode that enables the flash. Connects to the $CE\#$ pin on the Micron P30 or P33 flash. ⁽²⁾ |
| | | | | This pin has an internal pull-up resistor that is always active. |

| Table 8-20 | . Dedicated | Configuration | Pins on th | ne Cyclone | IV Device | (Part 2 of 4) |
|------------|-------------|---------------|------------|------------|-----------|---------------|
|------------|-------------|---------------|------------|------------|-----------|---------------|

Document Revision History

Table 10–3 lists the revision history for this chapter.

Table 10–3. Document Revision History

| Date | Version | Changes |
|---------------|---------|--|
| December 2013 | 1.3 | Updated the "EXTEST_PULSE" section. |
| November 2011 | 1.0 | Updated the "BST Operation Control" section. |
| | 1.2 | ■ Updated Table 10–2. |
| | | Added Cyclone IV E devices in Table 10–1 and Table 10–2 for the Quartus II software version 9.1 SP1 release. |
| February 2010 | 1.1 | ■ Updated Figure 10–1 and Figure 10–2. |
| | | Minor text edits. |
| November 2009 | 1.0 | Initial release. |

Section I. Transceivers

This section provides a complete overview of all features relating to the Cyclone[®] IV device transceivers. This section includes the following chapters:

- Chapter 1, Cyclone IV Transceivers Architecture
- Chapter 2, Cyclone IV Reset Control and Power Down
- Chapter 3, Cyclone IV Dynamic Reconfiguration

Revision History

Refer to the chapter for its own specific revision history. For information about when the chapter was updated, refer to the Chapter Revision Dates section, which appears in the complete handbook.

Transmitter Channel Datapath

The following sections describe the Cyclone IV GX transmitter channel datapath architecture as shown in Figure 1–3:

- TX Phase Compensation FIFO
- Byte Serializer
- 8B/10B Encoder
- Serializer
- Transmitter Output Buffer

TX Phase Compensation FIFO

The TX phase compensation FIFO compensates for the phase difference between the low-speed parallel clock and the FPGA fabric interface clock, when interfacing the transmitter channel to the FPGA fabric (directly or through the PIPE and PCIe hard IP). The FIFO is four words deep, with latency between two to three parallel clock cycles. Figure 1–4 shows the TX phase compensation FIFO block diagram.

Figure 1–4. TX Phase Compensation FIFO Block Diagram



Note to Figure 1-4:

(1) The x refers to the supported 8-, 10-, 16-, or 20-bits transceiver channel width.

- The FIFO can operate in registered mode, contributing to only one parallel clock cycle of latency in Deterministic Latency functional mode. For more information, refer to "Deterministic Latency Mode" on page 1–73.
- **To** For more information about FIFO clocking, refer to "FPGA Fabric-Transceiver Interface Clocking" on page 1–43.

Byte Serializer

The byte serializer divides the input datapath width by two to allow transmitter channel operation at higher data rates while meeting the maximum FPGA fabric frequency limit. This module is required in configurations that exceed the maximum FPGA fabric-transceiver interface clock frequency limit and optional in configurations that do not.

• For the FPGA fabric-transceiver interface frequency specifications, refer to the *Cyclone IV Device Data Sheet*.



Figure 1–37. Clock Distribution in Bonded (×2 and ×4) Channel Configuration for Transceivers in F484 and Larger Packages

Notes to Figure 1-37:

- (1) High-speed clock.
- (2) Low-speed clock.
- (3) Bonded common low-speed clock path.
- (4) These PLLs have restricted clock driving capability and may not reach all connected channels. For details, refer to Table 1–10.

The channel datapath clocking is similar between bonded channels in ×2 and ×4 configurations.

Figure 1–38 shows the datapath clocking in Transmitter Only operation for ×2 and ×4 bonded configurations. In these configurations, each bonded channel selects the high-speed clock from one the supported PLLs. The high-speed clock in each bonded channel feeds the respective serializer for parallel to serial operation. The common bonded low-speed clock feeds to each bonded channel that is used for the following blocks in each transmitter PCS channel:

- 8B/10B encoder
- read clock of byte serializer
- read clock of TX phase compensation FIFO

PIPE Interface

The PIPE interface provides a standard interface between the PCIe-compliant PHY and MAC layer as defined by the version 2.00 of the PIPE Architecture specification for Gen1 (2.5 Gbps) signaling rate. Any core or IP implementing the PHY MAC, data link, and transaction layers that supports PIPE 2.00 can be connected to the Cyclone IV GX transceiver configured in PIPE mode. Table 1–15 lists the PIPE-specific ports available from the Cyclone IV GX transceiver configured in PIPE mode and the corresponding port names in the PIPE 2.00 specification.

| Transceiver Port Name | PIPE 2.00 Port Name |
|----------------------------------|---------------------|
| tx_datain[150] ⁽¹⁾ | TxData[150] |
| <pre>tx_ctrlenable[10] (1)</pre> | TxDataK[10] |
| rx_dataout[150] ⁽¹⁾ | RxData[150] |
| rx_ctrldetect[10] ⁽¹⁾ | RxDataK[10] |
| tx_detectrxloop | TxDetectRx/Loopback |
| tx_forceelecidle | TxElecIdle |
| tx_forcedispcompliance | TxCompliance |
| pipe8b10binvpolarity | RxPolarity |
| powerdn[10] ⁽²⁾ | PowerDown[10] |
| pipedatavalid | RxValid |
| pipephydonestatus | PhyStatus |
| pipeelecidle | RxElecIdle |
| pipestatus | RxStatus[20] |

Table 1–15. Transceiver-FPGA Fabric Interface Ports in PIPE Mode

Notes to Table 1-15:

(1) When used with PCIe hard IP block, the byte SERDES is not used. In this case, the data ports are 8 bits wide and control identifier is 1 bit wide.

(2) Cyclone IV GX transceivers do not implement power saving measures in lower power states (P0s, P1, and P2), except when putting the transmitter buffer in electrical idle in the lower power states.

Receiver Detection Circuitry

In PIPE mode, the transmitter supports receiver detection function with a built-in circuitry in the transmitter PMA. The PCIe protocol requires the transmitter to detect if a receiver is present at the far end of each lane as part of the link training and synchronization state machine sequence. This feature requires the following conditions:

- transmitter output buffer to be tri-stated
- have OCT utilization
- 125 MHz clock on the fixedclk port

The circuit works by sending a pulse on the common mode of the transmitter. If an active PCIe receiver is present at the far end, the time constant of the step voltage on the trace is higher compared to when the receiver is not present. The circuitry monitors the time constant of the step signal seen on the trace to decide if a receiver was detected.

PCIe Functional Mode

You can configure PCIe functional mode with or without the receiver clock rate compensation FIFO in the Cyclone IV GX device. The reset sequence remains the same whether or not you use the receiver clock rate compensation FIFO.

PCIe Reset Sequence

The PCIe protocol consists of an initialization/compliance phase and a normal operation phase. The reset sequences for these two phases are described based on the timing diagram in Figure 2–10.

Figure 2–10. Reset Sequence of PCIe Functional Mode (1), (2)



Notes to Figure 2–10:

- (1) This timing diagram is drawn based on the PCIe Gen 1×1 mode.
- (2) For bonded PCIe Gen 1 ×2 and ×4 modes, there will be additional rx freqlocked [n] signal. n=number of channels.
- (3) For t_{LTD Manual} duration, refer to the Cyclone IV Device Datasheet chapter.
- (4) For t_{LTD Auto} duration, refer to the *Cyclone IV Device Datasheet* chapter.
- (5) The busy signal is asserted and deasserted only during initial power up when offset cancellation occurs. In subsequent reset sequences, the busy signal is asserted and deasserted only if there is a read or write operation to the ALTGX_RECONFIG megafunction.

| Symbol | Modes | | C6 | | | C7, I | 7 | | C8, A | 7 | | C8L, I | BL | | C9L | | llnit |
|------------------------------|-------|-----|-----|-----|-----|-------|-----|-----|-------|-----|-----|--------|-----|-----|-----|-----|-------|
| | | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Unit |
| t _{LOCK} <i>(3)</i> | | | | 1 | | | 1 | | | 1 | — | _ | 1 | | | 1 | ms |

Table 1–31. RSDS Transmitter Timing Specifications for Cyclone IV Devices (1), (2), (4) (Part 2 of 2)

Notes to Table 1-31:

(1) Applicable for true RSDS and emulated RSDS_E_3R transmitter.

(2) Cyclone IV E devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 1, 2, 5, and 6. Emulated RSDS transmitter is supported at the output pin of all I/O Banks. Cyclone IV GX devices—true RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the output pin of Row I/O Banks 5 and 6. Emulated RSDS transmitter is only supported at the

pin of I/O Banks 3, 4, 5, 6, 7, 8, and 9.
(3) t_{LOCK} is the time required for the PLL to lock from the end-of-device configuration.

(4) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

| Symbol | Modes | C6 | | C7, I7 | | C8, A7 | | C8L, 18L | | C9L | | Ilmit | | | | | |
|--|-----------------------------|-----|-----|--------|-----|--------|-----|----------|-----|-----|-----|-------|-----|-----|-----|------|------|
| | | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | Min | Тур | Max | |
| f _{HSCLK} (input clock frequency) | ×10 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 72.5 | MHz |
| | ×8 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 72.5 | MHz |
| | ×7 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 72.5 | MHz |
| | ×4 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 72.5 | MHz |
| | ×2 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 85 | 5 | — | 72.5 | MHz |
| | ×1 | 5 | — | 170 | 5 | — | 170 | 5 | — | 170 | 5 | — | 170 | 5 | — | 145 | MHz |
| Device operation in Mbps | ×10 | 100 | — | 170 | 100 | — | 170 | 100 | — | 170 | 100 | — | 170 | 100 | — | 145 | Mbps |
| | ×8 | 80 | — | 170 | 80 | — | 170 | 80 | — | 170 | 80 | — | 170 | 80 | — | 145 | Mbps |
| | ×7 | 70 | — | 170 | 70 | — | 170 | 70 | — | 170 | 70 | — | 170 | 70 | — | 145 | Mbps |
| | ×4 | 40 | — | 170 | 40 | — | 170 | 40 | — | 170 | 40 | — | 170 | 40 | — | 145 | Mbps |
| | ×2 | 20 | — | 170 | 20 | — | 170 | 20 | — | 170 | 20 | — | 170 | 20 | — | 145 | Mbps |
| | ×1 | 10 | — | 170 | 10 | — | 170 | 10 | — | 170 | 10 | — | 170 | 10 | — | 145 | Mbps |
| t _{DUTY} | — | 45 | — | 55 | 45 | — | 55 | 45 | — | 55 | 45 | — | 55 | 45 | — | 55 | % |
| TCCS | _ | — | — | 200 | — | — | 200 | — | — | 200 | — | — | 200 | — | — | 200 | ps |
| Output jitter (peak to peak) | _ | _ | _ | 500 | _ | _ | 500 | _ | _ | 550 | _ | _ | 600 | _ | _ | 700 | ps |
| t _{RISE} | 20-80%, | | | | | | | | | | | | | | | | |
| | C _{LOAD} = 5 pF | - | 500 | _ | - | 500 | _ | _ | 500 | _ | _ | 500 | - | — | 500 | _ | ps |
| | 20-80%, | | | 1 | | | 1 | | | 1 | | | | | | | |
| t _{FALL} | C _{LOAD} = 5 pF | — | 500 | - | - | 500 | - | - | 500 | - | - | 500 | - | | 500 | - | ps |

 Table 1–32. Emulated RSDS_E_1R Transmitter Timing Specifications for Cyclone IV Devices (1), (3) (Part 1 of 2)

• For more information about the supported maximum clock rate, device and pin planning, IP implementation, and device termination, refer to *Section III: System Performance Specifications* of the *External Memory Interface Handbook*.

Table 1-37 lists the memory output clock jitter specifications for Cyclone IV devices.

Table 1–37. Memory Output Clock Jitter Specifications for Cyclone IV Devices (1), (2)

| Parameter | Symbol | Min | Max | Unit |
|------------------------------|------------------------|------|-----|------|
| Clock period jitter | t _{JIT(per)} | -125 | 125 | ps |
| Cycle-to-cycle period jitter | t _{JIT(cc)} | -200 | 200 | ps |
| Duty cycle jitter | t _{JIT(duty)} | -150 | 150 | ps |

Notes to Table 1-37:

- (1) Memory output clock jitter measurements are for 200 consecutive clock cycles, as specified in the JEDEC DDR2 standard.
- (2) The clock jitter specification applies to memory output clock pins generated using DDIO circuits clocked by a PLL output routed on a global clock (GCLK) network.

Duty Cycle Distortion Specifications

Table 1–38 lists the worst case duty cycle distortion for Cyclone IV devices.

Table 1–38. Duty Cycle Distortion on Cyclone IV Devices I/O Pins (1), (2), (3)

| Symbol | C6 | | C7 | , 17 | C8, I8 | BL, A7 | C9L | | Unit | |
|-------------------|-----|-----|-----|------|--------|--------|-----|-----|------|--|
| Symbol | Min | Max | Min | Max | Min | Max | Min | Max | Unit | |
| Output Duty Cycle | 45 | 55 | 45 | 55 | 45 | 55 | 45 | 55 | % | |

Notes to Table 1-38:

(1) The duty cycle distortion specification applies to clock outputs from the PLLs, global clock tree, and IOE driving the dedicated and general purpose I/O pins.

(2) Cyclone IV devices meet the specified duty cycle distortion at the maximum output toggle rate for each combination of I/O standard and current strength.

(3) Cyclone IV E 1.0 V core voltage devices only support C8L, C9L, and I8L speed grades. Cyclone IV E 1.2 V core voltage devices only support C6, C7, C8, I7, and A7 speed grades. Cyclone IV GX devices only support C6, C7, C8, and I7 speed grades.

OCT Calibration Timing Specification

Table 1–39 lists the duration of calibration for series OCT with calibration at device power-up for Cyclone IV devices.

Table 1–39. Timing Specification for Series OCT with Calibration at Device Power-Up for Cyclone IV Devices $^{(1)}$

| Symbol | Description | Maximum | Units |
|---------------------|---|---------|-------|
| t _{octcal} | Duration of series OCT with calibration at device power-up | 20 | μs |

Note to Table 1-39:

(1) OCT calibration takes place after device configuration and before entering user mode.